

ABSTRACT

A pattern inspection method in which an image can be detected without an image detection error due to an adverse effect to be given by such factors as ions implanted in a wafer, pattern connection/no-connection, and pattern edge formation. A digital image of an object substrate is attained through microscopic observation thereof, the attained digital image is examined to detect defects while masking a region pre-registered in terms of coordinates or while masking a pattern meeting a pre-registered pattern, and an image of each of the defects thus detected is displayed. Further, each of the defects detected using the digital image attained through microscopic observation is checked to judge whether its feature meets a pre-registered feature or not. Defects having a feature that meets the pre-registered feature are so displayed that they can be turned/offset, or they are so displayed as to be distinguishable from the other defects.